#### [Causes/processes involved/keys to judgment]

The defect is caused by an uneven thickness of solder resist due to recessing of coated solder resist or uneven coating of solder resist (Solder resist curing process)

## 2-3-1-8 鉄基板 SR 傷/铁基板的 SR 划伤 / Scraped solder resist on iron-base printed board

【特徴】幅広くSRが削り取られている状態の欠陥、 露出部の鉄表面に錆が見られる

【特征】SR 被大面积削掉的缺陷,露出部位的铁氧化。

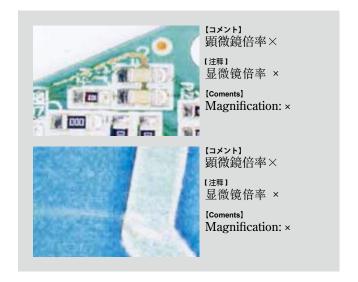
**[Characteristics]** Solder resist is widely scraped off. The exposed iron-board surface is often rusted.

【原因・判断ポイント・発生工程】鉄基板製品が重なり装置に挟まるなどにより、SR部が削り取られたりして出来たもの(SR塗布工程後)

【原因、判断要点、发生工序】由于铁基板重叠,被夹在装置里,SR 部位被削掉所引起的(SR 涂布工序后)。

### [Causes/processes involved/keys to judgment]

Iron-base printed boards are stacked or pinched in the machine and solder resist is scraped off to cause the defect. (After solder resist application process)



# 2-3-2 その他 (SR その他欠陥) / 其它 (SR 及其它的缺陷) /

Other solder resist related defects

## 2-3-2-1 SR 被り/SR 爬上导线/Solder resist left on conductor to be exposed

【特徴】SRが、導体上に部分的に被っている状態の欠陥、同一個所欠陥となることが多い

【特征】SR 爬上导线局部的缺陷,大多数是定位性的 缺陷。

**[Characteristics]** Solder resist covers partially on the conductor to be exposed. Often the defect occurs on the same position of all the products.

【原因・判断ポイント・発生工程】 S R 印刷版裏の 汚れや A W F のピンホールなどにより出来たもの (SRパターン印刷、焼付露光工程)

